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(12) **United States Design Patent** (10) **Patent No.:** **US D825,498 S**
Allin et al. (45) **Date of Patent:** **** Aug. 14, 2018**

- (54) **HEAT SINK ASSEMBLY** 2013/0070418 A1* 3/2013 Lee H01L 23/4006
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(US) 361/700
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(US) 2013/0077251 A1* 3/2013 Yang G06F 1/20
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(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179, 122, 182
CPC .. H05K 7/20; H05K 7/20172; H05K 7/20127;
H05K 7/20336; H05K 7/202; H05K
7/20272; H01L 23/34; H01L 23/3672;
H01L 23/40; H01L 23/4006; H01L
23/4093; F28D 15/0208; F28D 15/04
See application file for complete search history.

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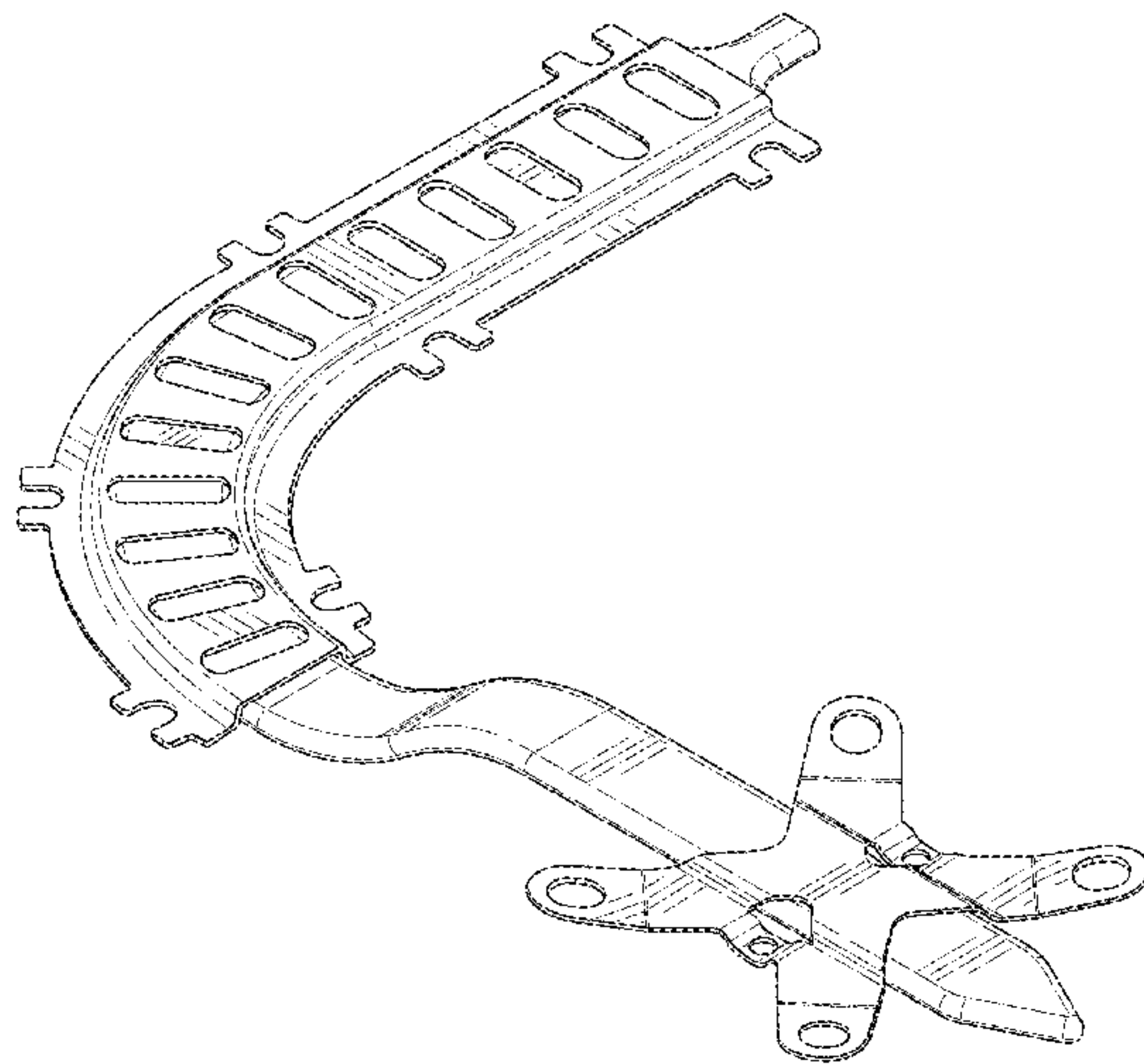
(57) **CLAIM**

The ornamental design for a heat sink assembly, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a heat sink assembly, showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a left side view thereof;
FIG. 5 is a right side view thereof;
FIG. 6 is a top view thereof; and,
FIG. 7 is a bottom view thereof.

1 Claim, 7 Drawing Sheets



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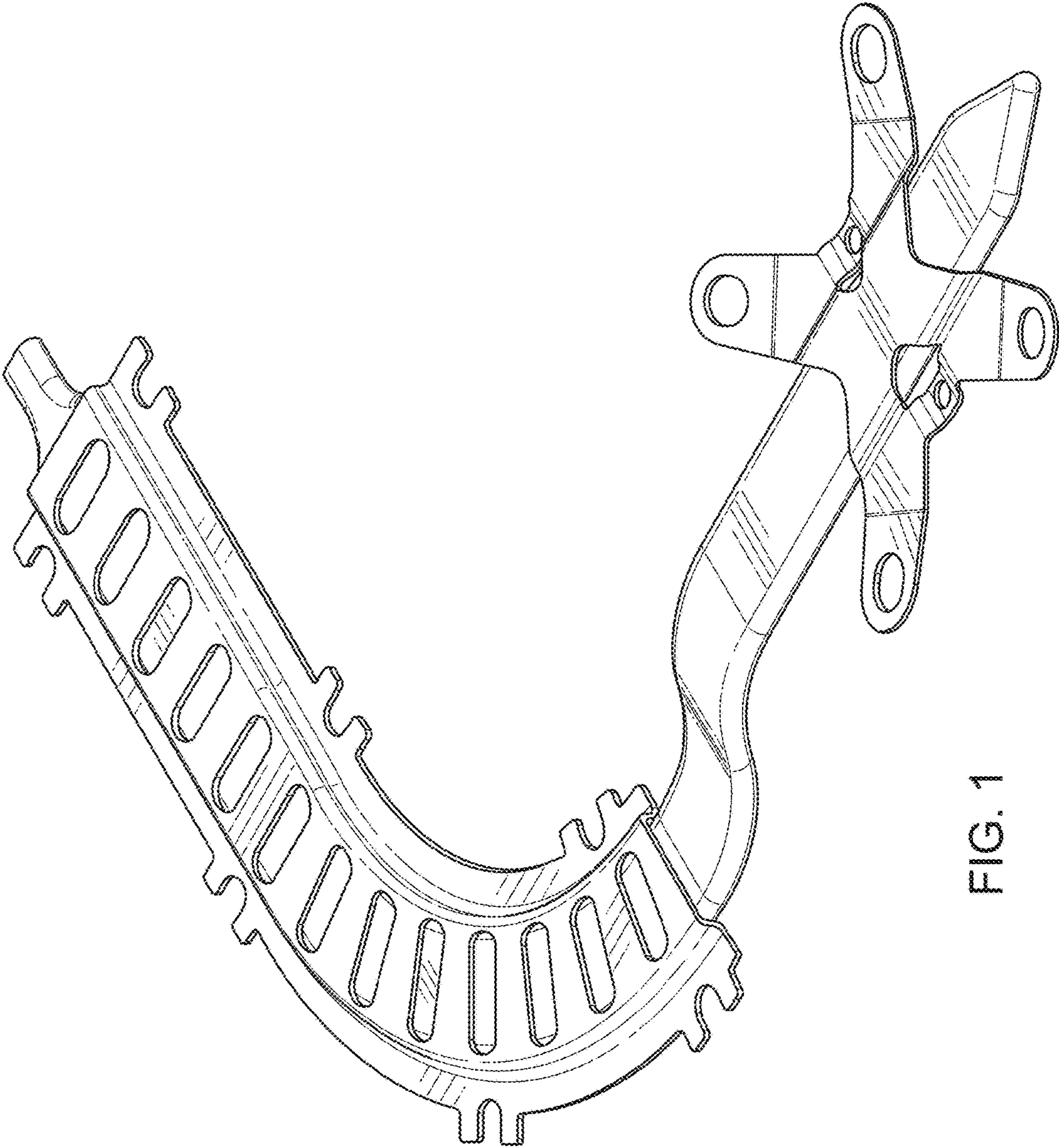


FIG. 1

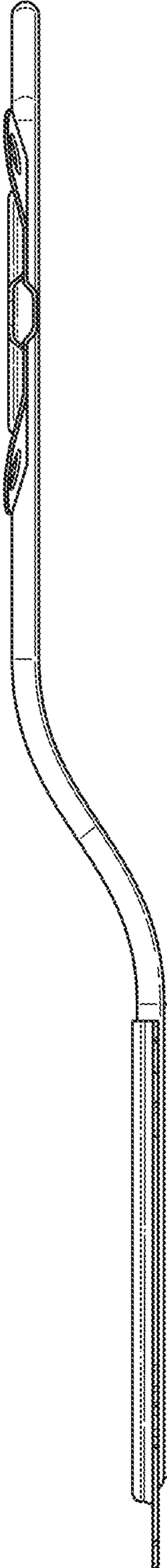


FIG. 2

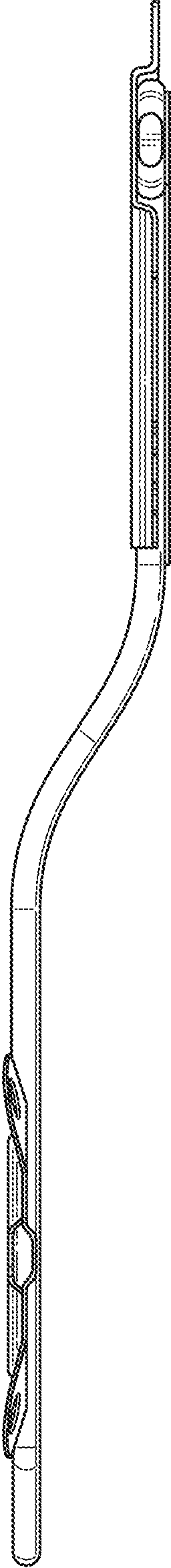


FIG. 3

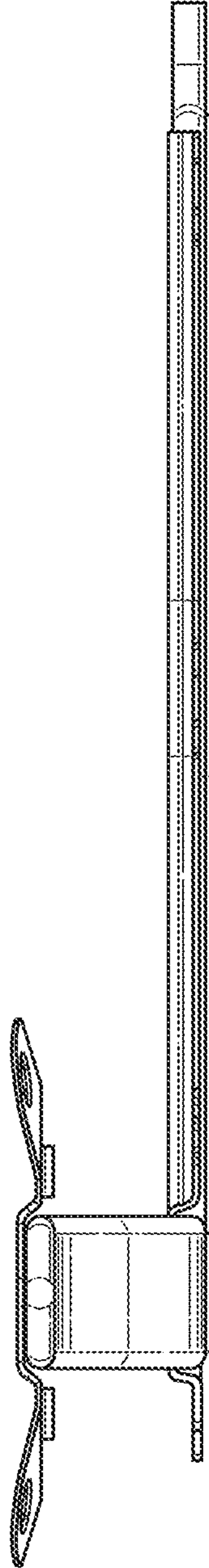


FIG. 4

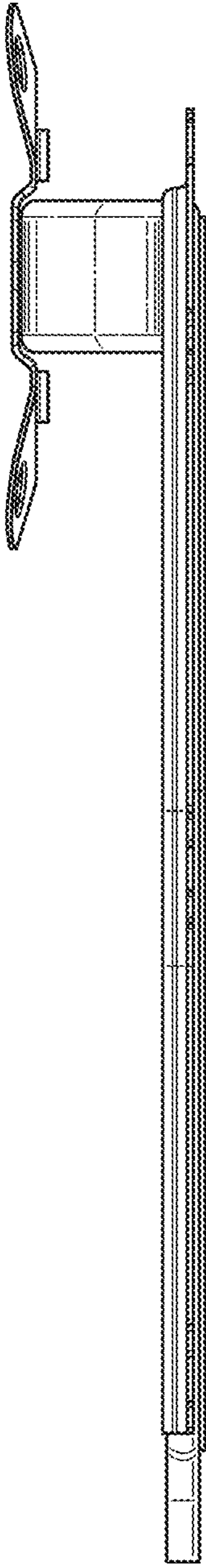


FIG. 5

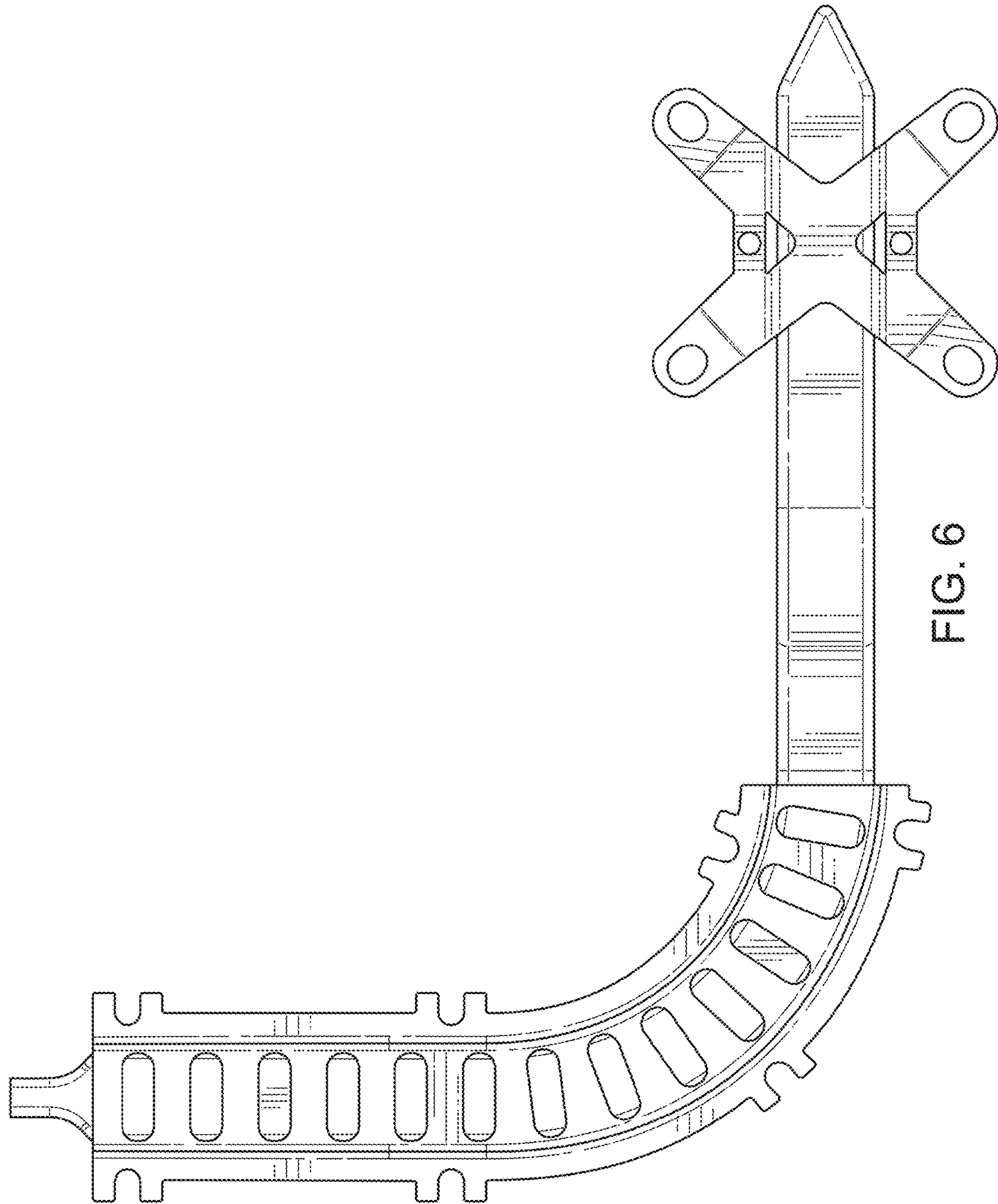


FIG. 6

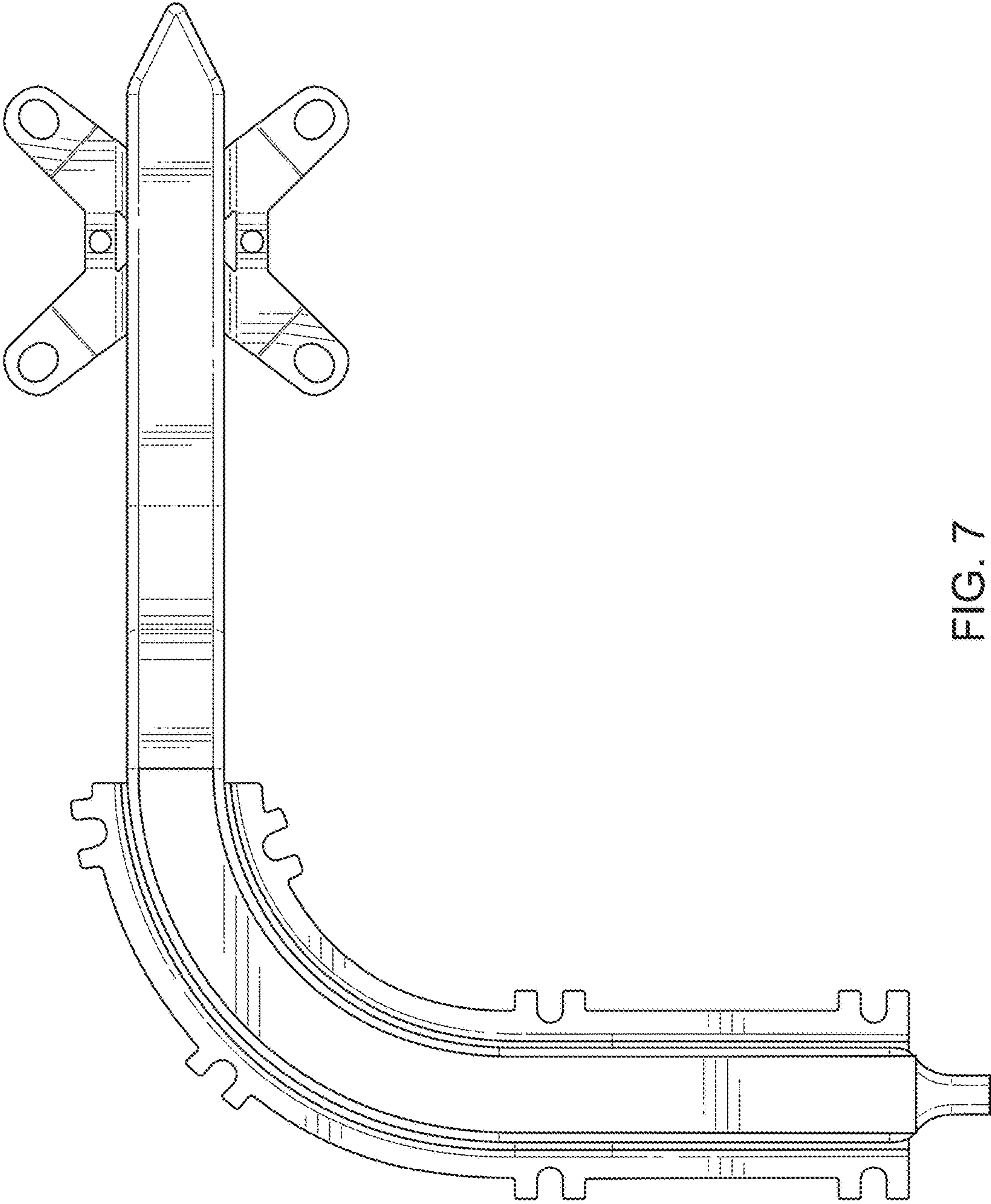


FIG. 7